BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-Low Profile





ATS Part#: ATS-51450R-C0-R0

Description: 45.00 x 45.00 x 19.50 mm BGA Heat Sink - High

Performance maxiFLOW/maxiGRIP-Low Profile

Heat Sink Type: maxiFLOW
Heat Sink Attachment: maxiGRIP

Equivalent Part Number: See below for part numbes with TIM

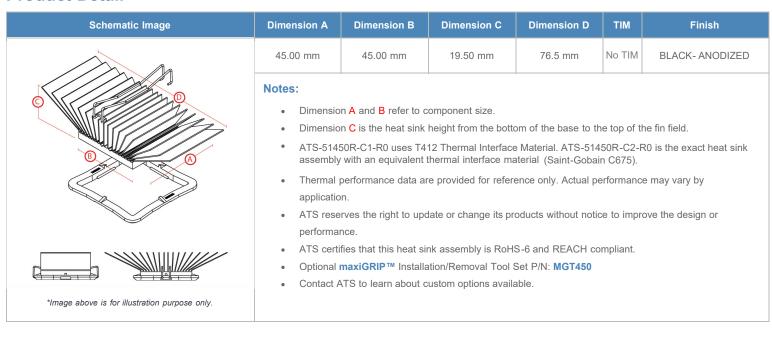
Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- · Does not come preassembled with high performance thermal interface material
- Designed for low profile components from 1.5 to 2.99mm

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	1.6 °C/W	1.3 °C/W	1.1 °C/W	1 °C/W	0.9 °C/W	0.8 °C/W	0.8 °C/W
	Ducted Flow	1.2	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail







^{*}Image above is for illustration purpose only.